

FEATURES

- | 90W Peak Pulse Power per Line (tp=8/20μs)
- | Protects Two High Speed Lines
- | Low Clamping Voltage
- | Working voltages : 5 V
- | Low leakage current

APPLICATIONS

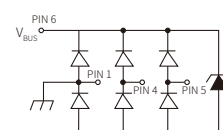
- | USB 3.0/USB 3.1 Interfaces
- | HDMI 1.4/HDMI 2.0 Interfaces
- | Video Graphics Cards
- | Keypads, Side Keys, LCD Displays
- | Notebooks & Desktop Computers
- | Portable Instrumentation
- | Peripherals



DFN1109MP6



Marking



Schematic Symbol

IEC COMPATIBILITY

- | IEC61000-4-2 (ESD) ±17kV (air), ±15kV (contact)
- | IEC61000-4-4 (EFT) 40A (5/50ns)

APPROVALS

- | | |
|-------------|------------------------------------|
| RoHS | Compliance with 2011/65/EU |
| HF | Compliance with IEC61249-2-21:2003 |

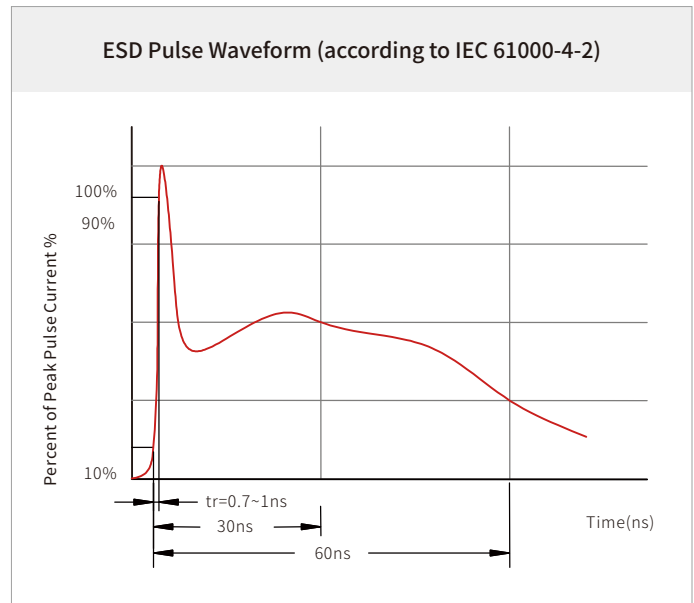
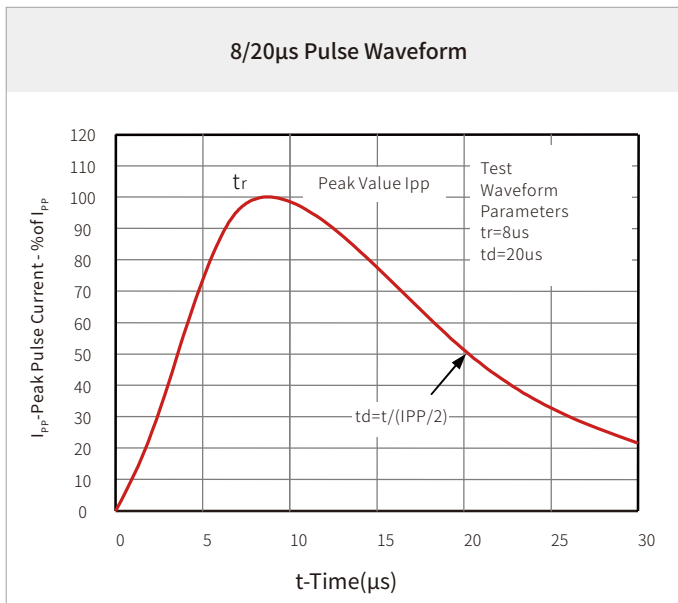
THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
P_{PP}	Peak Pulse Power (tp=8/20μs waveform)	90	Watts
T_J	Operating Temperature Range	-55 to +150	°C
T_{STG}	Storage Temperature Range	-55 to +150	°C

ELECTRICAL CHARACTERISTICS

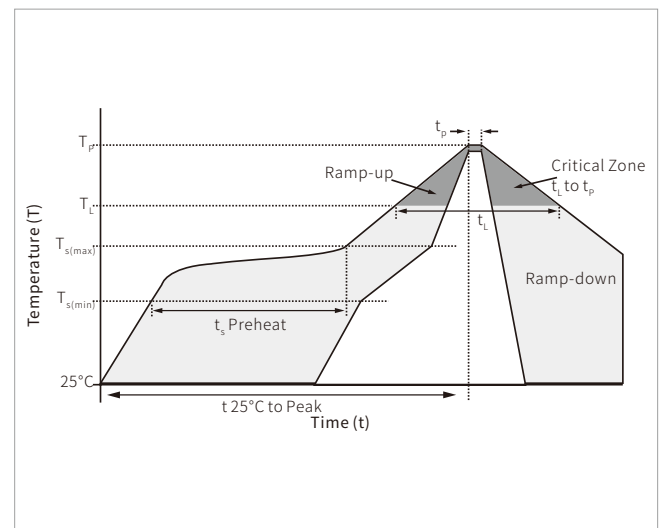
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{RWM}	Reverse Stand-off Voltage				5	V
V_{BR}	Reverse Breakdown Voltage	$I_T=1mA$	6			V
I_R	Reverse Leakage Current	$V_{RWM}=5V$			0.1	μA
V_C	Clamping Voltage	$I_{PP}=1A, tp=8/20\mu s$			18	V
V_C	Clamping Voltage	$I_{PP}=3A, tp=8/20\mu s$			30	V
I_{PP}	Peak Pulse Current	$tp=8/20\mu s$			3	A
C_J	Off State Junction Capacitance	$V_R=0V, f=1MHz$		0.25		pF

CHARACTERISTIC CURVES

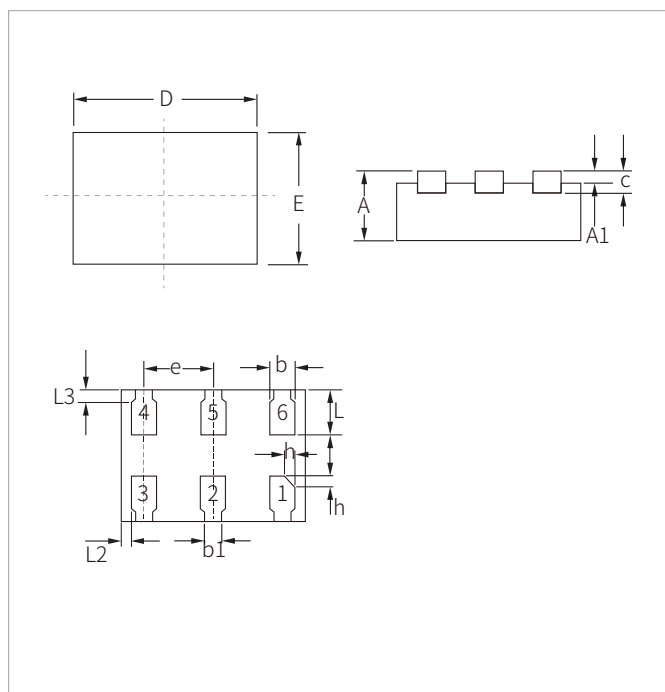


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

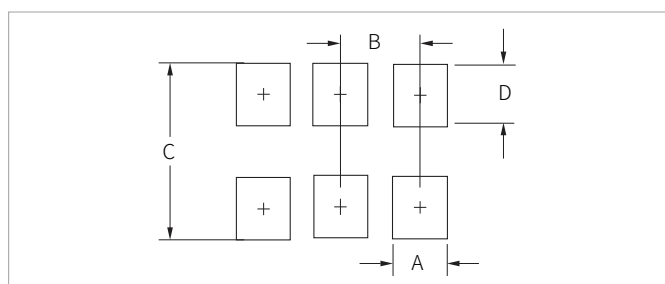


DFN1109MP6 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.40	0.60	0.016	0.024
A1	0	0.05	0	0.002
b	0.15	0.25	0.006	0.010
b1	0.14REF		0.005REF	
c	0.10	0.20	0.004	0.008
D	1.00	1.20	0.040	0.047
e	0.40BSC		0.016BSC	
E	0.80	1.00	0.031	0.040
L	0.30	0.40	0.012	0.016
L2	0.05REF		0.002REF	
L3	0.10REF		0.004REF	
h	0.05	0.15	0.008	0.012

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
	Nominal	Nominal
A	0.25	0.010
B	0.40	0.016
C	1.10	0.043
D	0.45	0.018

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SE11F09B5.0UD	DFN1109MP6	3000PCS	7"

Headquarters

No.3387 Shendu Road
Pujiang I&E Park
Minhang Shanghai China
201000

Hotline

400-021-5756

Web

<https://www.semiware.com>

Sales Center

Tel: 86-21-3463-7458
Email: sales18@semiware.com

Customer Service

Tel: 86-21-5484-1001
Email: sales17@semiware.com

Technical Support

Tel: 86-21-3463-7654
Email: fae01@semiware.com

Complaint & Suggestions

Tel: 86-21-3463-7172
Ext: 8868
Email: cs03@semiware.com

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Website



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